

Amendment Transmittal

TOWNSEND and TOWNSEND and CREW LLP
(650) 326-2400

Attorney Docket No. AM1126-D1/T8910
TTC Ref No. 016301-008910US

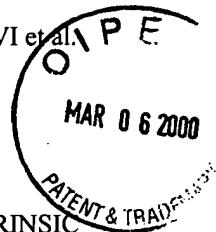
In re application of: KRAMADHATI V. RAVI et al.

Application No.: 09/362,504

Filed: July 27, 1999

Group Art Unit: 1763

For: METHOD FOR REDUCING THE INTRINSIC
STRESS OF HIGH DENSITY PLASMA FILMS



Date: Mar. 24, 2000

I hereby certify that this is being deposited with the United States
Postal Service as first class mail in an envelope addressed to:

Assistant Commissioner for Patents
Washington, D.C. 20231

Signed: Lynda Robisch

THE ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

Sir:

Transmitted herewith is an Amendment in the above-identified application. Also enclosed are the following:

Petition to Extend Time to Respond; and
 Return Receipt Postcard.

If any extension of time is needed, then this response should be considered a petition therefor.

The filing fee has been calculated as shown below:

	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA
TOTAL	* 21	MINUS	** 20	= 1
INDEP.	* 5	MINUS	*** 5	= 0
[] FIRST PRESENTATION OF MULTIPLE DEP. CLAIM				

SMALL ENTITY

RATE	ADDIT. FEE
x \$9.00 =	
x \$39.00 =	
+ \$130.00 =	
TOTAL	

OTHER THAN
SMALL ENTITY

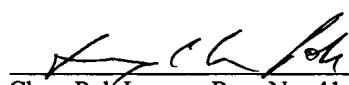
RATE	ADDIT. FEE
x \$18.00 =	\$18.00
x \$78.00 =	\$0.00
+ \$260.00 =	
TOTAL	\$18.00

Please charge Deposit Account No. 20-1430 as follows:

Claims fee \$18.00
 Any additional fees associated with this paper or during the pendency of this application.

2 extra copies of this sheet are enclosed.

TOWNSEND and TOWNSEND and CREW LLP


Chun-Pok Leung, Reg. No. 41,405

Attorneys for Applicant

PA 3053018 v1

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APR 04 2000

TECHNOLOGY CENTER 2800

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Assistant Commissioner for Patents
Washington, D.C. 20231

PATENT
Attorney Docket No.: AM1126-D1/T8910
TTC No. 16301-008910

MAR 06 2000

On Mar. 24, 2000
TOWNSEND and TOWNSEND and CREW LLP

By: Lynda Roboch

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

KRAMADHATI V. RAVI et al.

Application No.: 09/362,504

Filed: July 27, 1999

For: METHOD FOR REDUCING THE
INTRINSIC STRESS OF HIGH
DENSITY PLASMA FILMS

Examiner: Rudy Zervigon

Art Unit: 1763

AMENDMENT

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APR 04 2000

TECHNOLOGY CENTER 2800

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action mailed November 22, 1999, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend claims 16-18, 20, 26, 28, and 32; and add new claims 36. Note that the remaining claims are unamended, but are reproduced below for the Examiner's reference and convenience.

16. (Twice amended) An integrated circuit formed on a semiconductor substrate by the method of:

- a) flowing a process gas into a substrate processing chamber;
- b) forming a plasma from said process gas by coupling energy into said

substrate processing chamber;

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03/08/2000 SLM/MS 16.00 CH
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